



Gp #1742

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

A. David Johnson et. al.

Serial No.: 09/902,856

Filing Date: 7/10/01

For: Free Standing Shape Memory Alloy
Thin Film And Method

Art Unit: 1742

Examiner: Roy King

5/0

10/10/03

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on Feb 3, 2003.

Richard E. Backus, Reg. No. 22,701

Signed: Richard E. Backus

BOX NO FEE

Assistant Commissioner for Patents

Washington, D.C. 20231

AMENDMENT AND RESPONSE TO OFFICE ACTION

Sir:

In response to the office action of Oct. 24, 2002, please enter the following amendments (a marked-up version is on the attached sheet marked "Version With Markings To Show Changes Made").

Amended paragraph starting at line 4 on page 2 of specification:

Sputter deposited thin film shape memory alloys such as thin film comprised of TiNi overcomes these problems. Such films can be fabricated in a range of thickness from less than 1µm to 40µm. SMA material can be made in thin film configurations in accordance the teachings of U.S. patent No. 5,061,914 to Busch et. al., the disclosure of which is incorporated by this reference.

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